

Solder Paste

Solder Paste (SMT)	No Clean	Water Soluble	Lead-Free*	Low Temp*	Low TempSave*	Tin-Lead	Pin Testable	Ultra-low Voiding	Room Temp Storage	Flux Classification	Halogens
AMP One	X		X					X		ROLO	-
AMP One PT	X		X		X		X	X		ROLO	-
NL930PT	X		X			X	X			ROLO	-
NL932HF	X		X						X	ROLO	-
NC722	X			X			X			ROLO	-
NC676	X					X	X		X	ROLO	-
RMA250	X					X	X			ROL1	YES
AMP Wash		X	X					X		ORH1	YES
WS888		X	X							ORH0	YES
WS889		X	X			X				ORH1	YES
WS890		X	X							ORH1	YES
WS159		X				X				ORH0	YES
WS161		X				X				ORH1	YES

* Melting Points: Lead-Free (SAC305 217-220 °C, SN100CV 221-225 °C, LF-C2 208-213 °C), Low Temp (Sn42/Bi57/Ag1 138-140 °C), Low Temp (TempSave B37 139-174 °C), Tin-Lead (Sn63/Pb37 183 °C or Sn62/Pb36/Ag2 179 °C)

Solder Wire

Wire Solder	No Clean	Water Soluble	Tin Lead	SAC305	SN100C	Flux Classification	Halogens
Solid Core (no flux)	-	-			X	-	-
NC601	X			X	X	ROLO	-
WS101		X		X	X	ORH1	YES

Liquid Flux

Liquid Flux	No Clean	Water Soluble	Foaming	Spray	Rework	VOC Free	Solids Content (% wt)	Flux Classification	Halogens
NC120	X		X	X	X		2.0 - 2.2	ORL0	YES
NC160	X		X	X			5.5 - 6.0	ROLO	YES
NC165	X		X	X	X		3.4 - 3.8	ROLO	-
NC165-S	X		X	X			3.8 - 4.2	ROLO	YES
NC169	X		X	X			6.3 - 6.7	ROLO	YES
WIL-1	X	X	X	X	X	X	6.5 - 7.5	ORL0	YES
159HF		X	X	X	X		15.0 - 18.0	ORH0	-

Gel Flux

Gel Flux	No Clean	Water Soluble	Tin Lead	Lead Free	Print	Dispense	Pin Testable	Flux Classification	Halogens
Solder Paste Flux	X	X	X	X	X	X	*	*	*
NC26	X		X	X	X	X	X	ROLO	-
NC27	X		X	X	X	X	X	ROLO	YES
NC32	X		X	X	X	X		ROLO	-
WS89		X	X	X	X	X		ORH1	YES
WS90		X	X	X	X	X		ORH1	YES

* Dependent on Solder Paste

Solder Bar

Solder Alloy	Elemental Composition (approximate % wt)	Application	Melting Range (°C)
SN100C	Sn/0.7Cu/0.06Ni/0.005Ge	Wave, selective, dip, reflow, wire soldering	227
SN100Ce	Sn/0.06Ni/0.005Ge	Additive for SN100C pots when copper is high	230-232